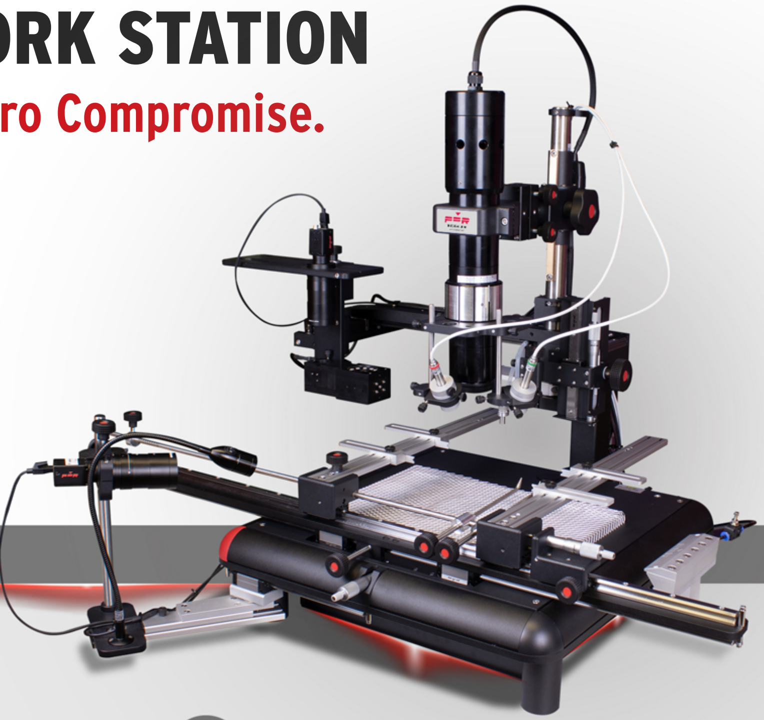
PDR | REWORK

IR-E3 PRO BGA REWORK STATION

Focused Infrared Precision, Zero Compromise.



OVERVIEW

The IR-E3 Pro is a high-performance manual rework system designed for large PCBs and high thermal mass components. Combining Focused Infrared heating with increased preheating capacity, advanced sensing, and precision alignment, it delivers maximum control and repeatability for demanding rework applications.

KEY ADVANTAGES

FOCUSED INFRARED & LARGE COMPONENT HEAD

- Visible, targeted focused IR heating directly to the component
- No damage to surrounding components
- Precise and adjustable energy for safe rework
- Large component head for components between 55mm and 85mm

PCB PREHEATER

- Protects components and PCBs from thermal shock
- Fast, even zonal PCB heating
- Reduces thermal gradients, warping, and board stress

THERMOACTIVE SOFTWARE

- Simple, intuitive interface for process control
- Automated temperature profiling and monitoring
- Ensures consistent, repeatable rework performance

SENSORS

- Non-contact infrared sensor for component temperature measurement
- Non-contact infrared sensor for accurate PCB temperature monitoring
- Enables independent control of component and PCB temperatures

ALIGNMENT SYSTEM

- Manual optical alignment system
- Accurate component positioning
- Designed for reliable, repeatable placement

TECHNICAL SPECIFICATIONS

Max PCB Size: 24 x 24"/620 x 620mm

Max Component Size: 3.3 x 3.3"/85 x 85mm

Min Component Size: 01005

Component Removal: Manual Pick-Up System

Component Placement: Split Beam Prism Alignment/x50 Magnification

Placement Accuracy: Up to 10um

Top Heater Power: 150W Focused Infrared up to Ø70mm Spot

PCB Preheater Power: 2800W Medium-Wave IR (3 Zones)

PCB Preheater Heating Area Size: 14.1 x 9.4"/360 x 240mm

Component Temperature Sensing: Non-Contact IR Sensor

PCB Temperature Sensing: Non-Contact IR Sensor

Number of TC Channels: 4

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